

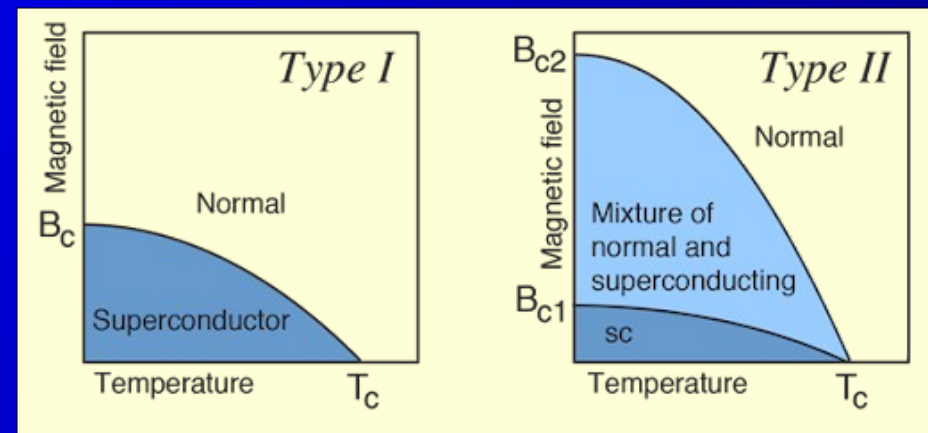
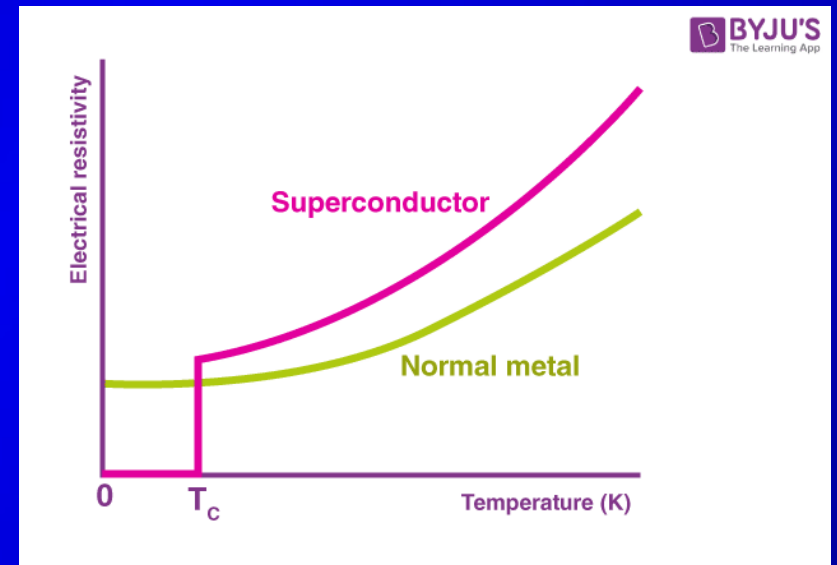
Thermal transmittance and Kapitza-resistance measurements of Nb₃Sn

After different treatments

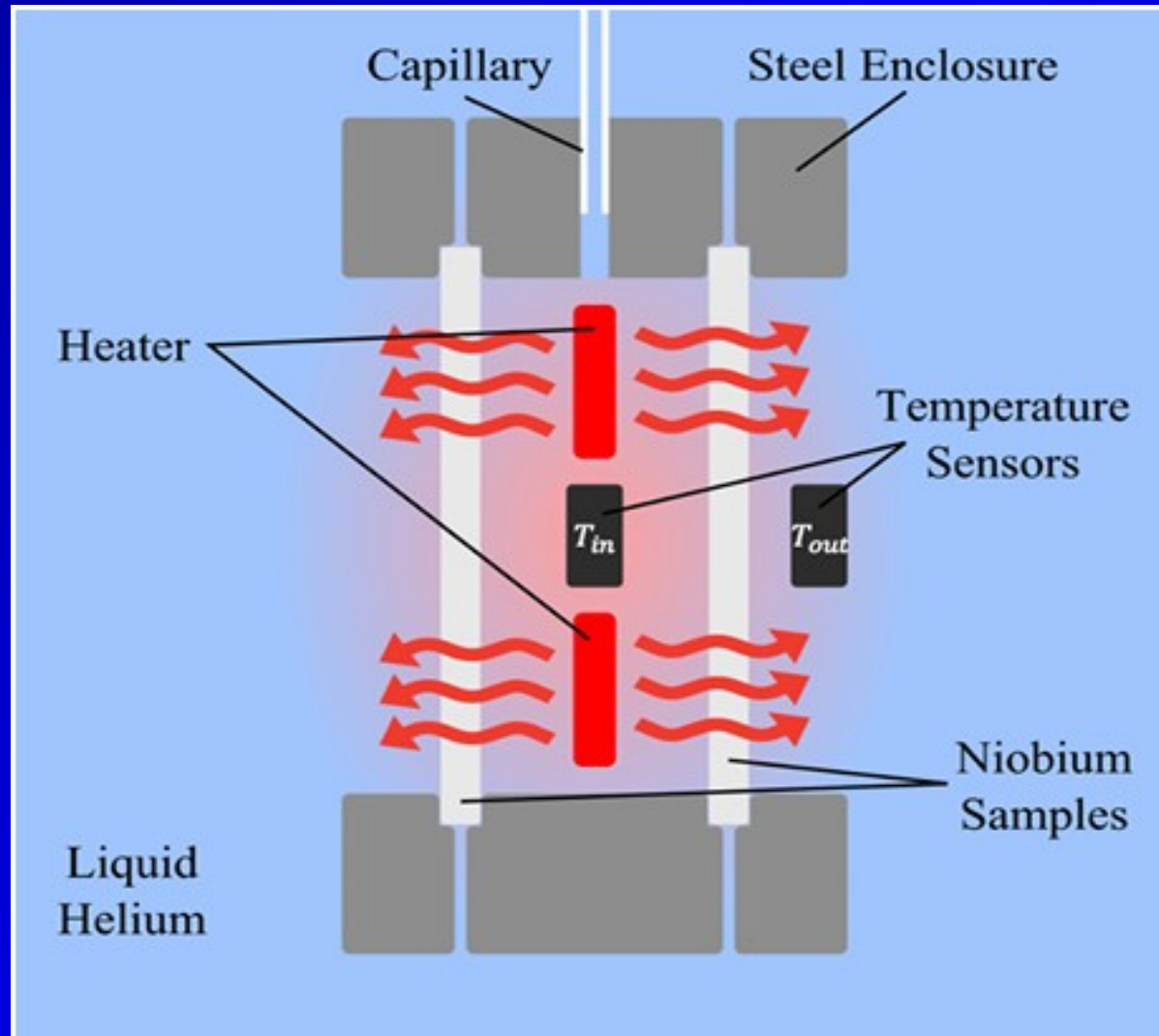
Motivation: Why?

Better heat transmittance:

- Heat build up because of cavity inaccuracies
- Cavity needs $T < T_c$
- Heat goes through cavity into helium bath



NTCI-Device



Measurements are taken below 2K

Thermal insulance

$$R_{ges} = \sum_{i,j} R_i + R_{i,j}$$

$$R_{i,j} = \frac{\Delta T_{i,j}}{q}$$

$$R_i = \frac{d_i}{\lambda_i}$$

R_{ges} is the total thermal transmittance resistance

$R_{i,j}$ is the resistance between layers (interface resistance)

R_i is the resistance for a material

$\Delta T_{i,j}$ is the temperature difference between layers

q is heat flux

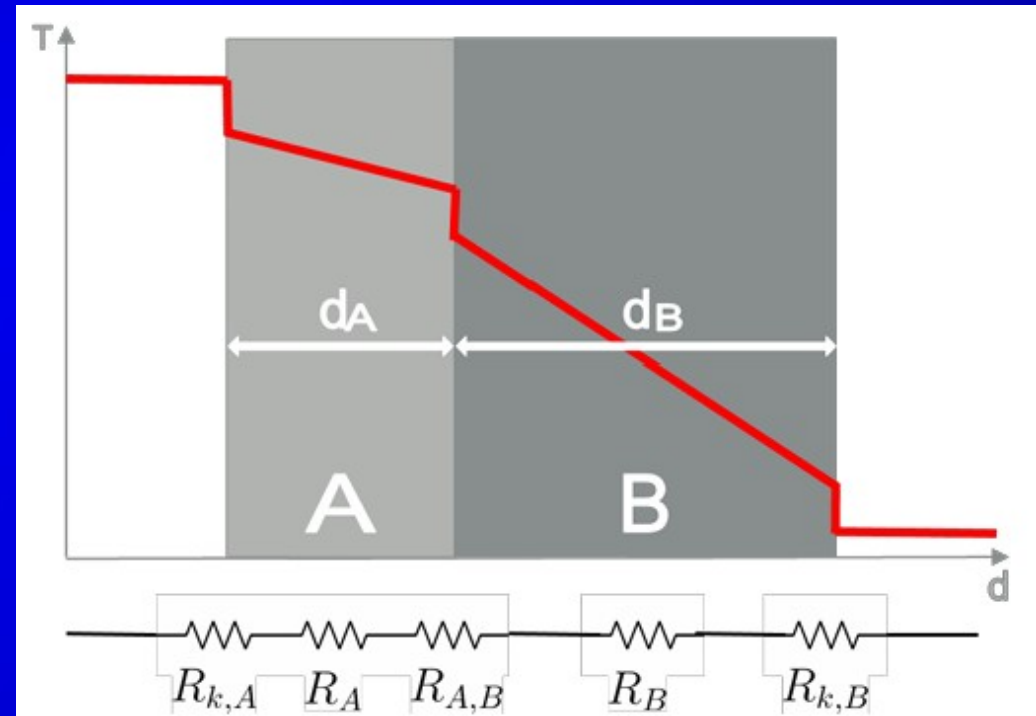
d is thickness

λ is thermal transmittance

Thermal insulance

- Heat propagates through electrons and phonons
- Phonons can't easily couple between materials

$$R_{ges} = \sum_{i,j} R_i + R_{i,j}$$



Thermal transmittance

K is thermal transmittance

K_0 is thermal transmittance without leaks

\dot{Q}_0 is norm const.

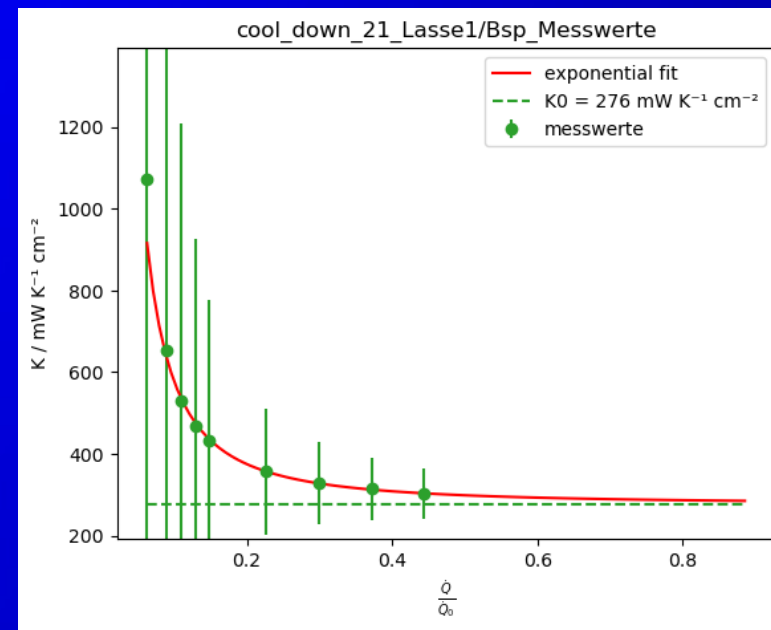
\dot{Q} is heat flux

n , a are fit parameters

$$K(\dot{Q}) = K_0 + a \left(\frac{\dot{Q}}{\dot{Q}_0} \right)^{-n}$$

$$\dot{Q}_0 = \left(\frac{0.01 K_0}{a} \right)^{-\frac{1}{n}}$$

the plot with fit is only meant as a example



Thermal transmittance

K is thermal transmittance (total)

\dot{q} is heat flux density

$\lambda(T)$ is heat transmittance

T is temperature

d is thickness

R_k is interface resistance

R is resistance

I Is Current

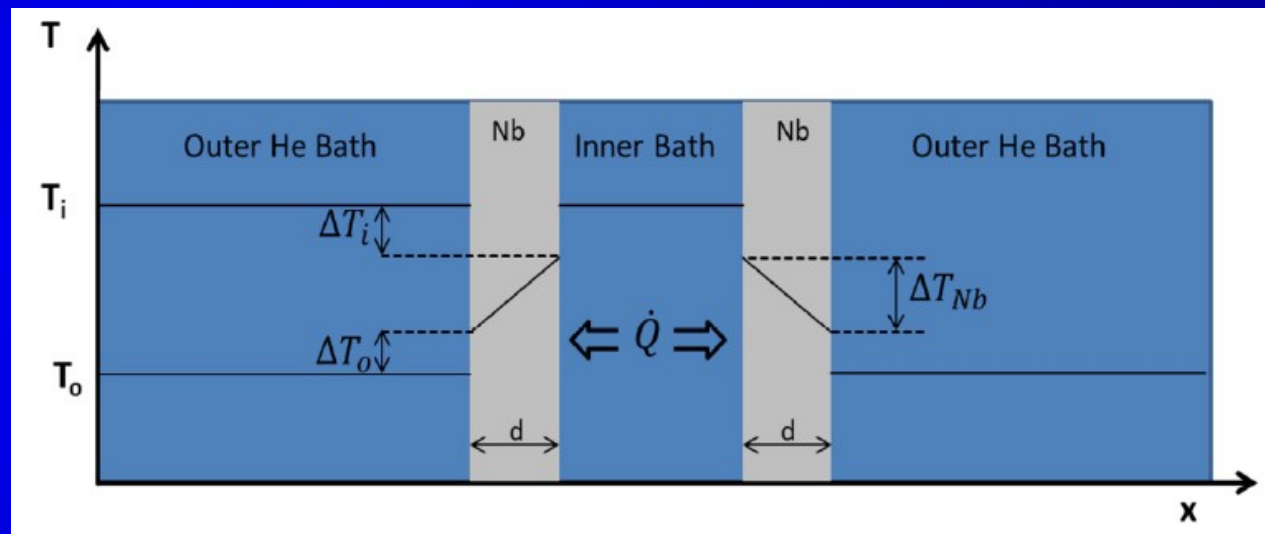
U Is Voltage

P Is Power

$$\dot{q} = \lambda(T) \cdot \vec{\nabla} T$$

$$K = \left(\frac{d}{\lambda} + R_k \right)^{-1} = \frac{1}{R}$$

$$I \cdot U = P = \dot{Q}$$



Nb₃Sn: Basics

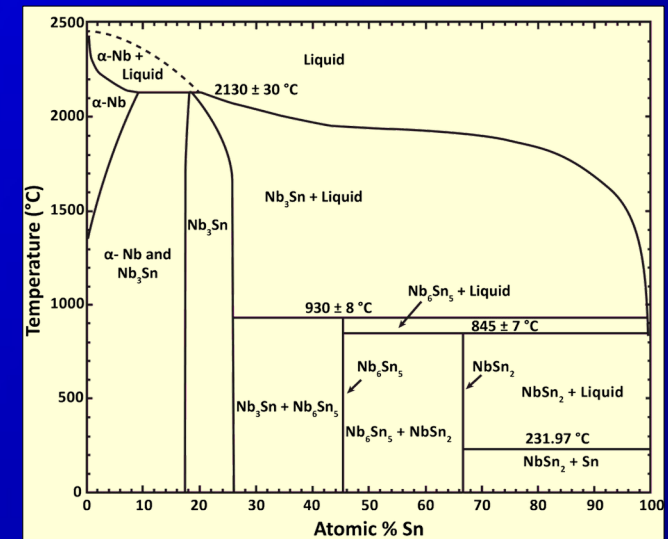
- 3 Niobium per 1 tin
- $T_{c,Nb3Sn} = 18.3\text{ K}$

Problems:

- Exact mixing Not possible
→ Low B_c
- Complicated Phase diagram

Table 1. Material parameters of Nb and Nb₃Sn.

Property	Nb	Nb ₃ Sn
T_c [K]	9.25 [3]	18 [1]
$\kappa(0K)$	1.4 [3]	34 [1]
ξ_0 [nm]	39 [4]	5.7(0.6) [5]
λ_L [nm]	27(3) [6]	65[7]–89[8]
$\mu_0 H_{c1}(0K)$ [mT]	174 [3]	38 [1]
$\mu_0 H_c(0K)$ [mT]	199 [3]	520 [1]
$\mu_0 H_{sh}(0K)$ [mT]	240 [2]	440 [2]



<https://en.wikipedia.org/wiki/Niobium%E2%80%93tin>

Coating

Nb₃Sn & CuBL:

- Good thermal conductivity
- Brittle
- Cu has low melting point
- Nb₃Sn (200nm), Nb (30μm)

(Not representative of our coating)



<https://leadrp.net/de/blog/powder-coating-a-commonly-used-surface-finish-process-overview/>

Baseline

Buffered Chemical Polishing (BCP)

- 130 μm removed
- Exothermal reaction cooled to $\sim 10^{\circ}\text{C}$
- Hydrogen enters the material

Outgassing annealing

- 3h at 800°C
- 10^{-6} mbar



Mid-T

- Medium Temp. ca. 300°C
- 3h

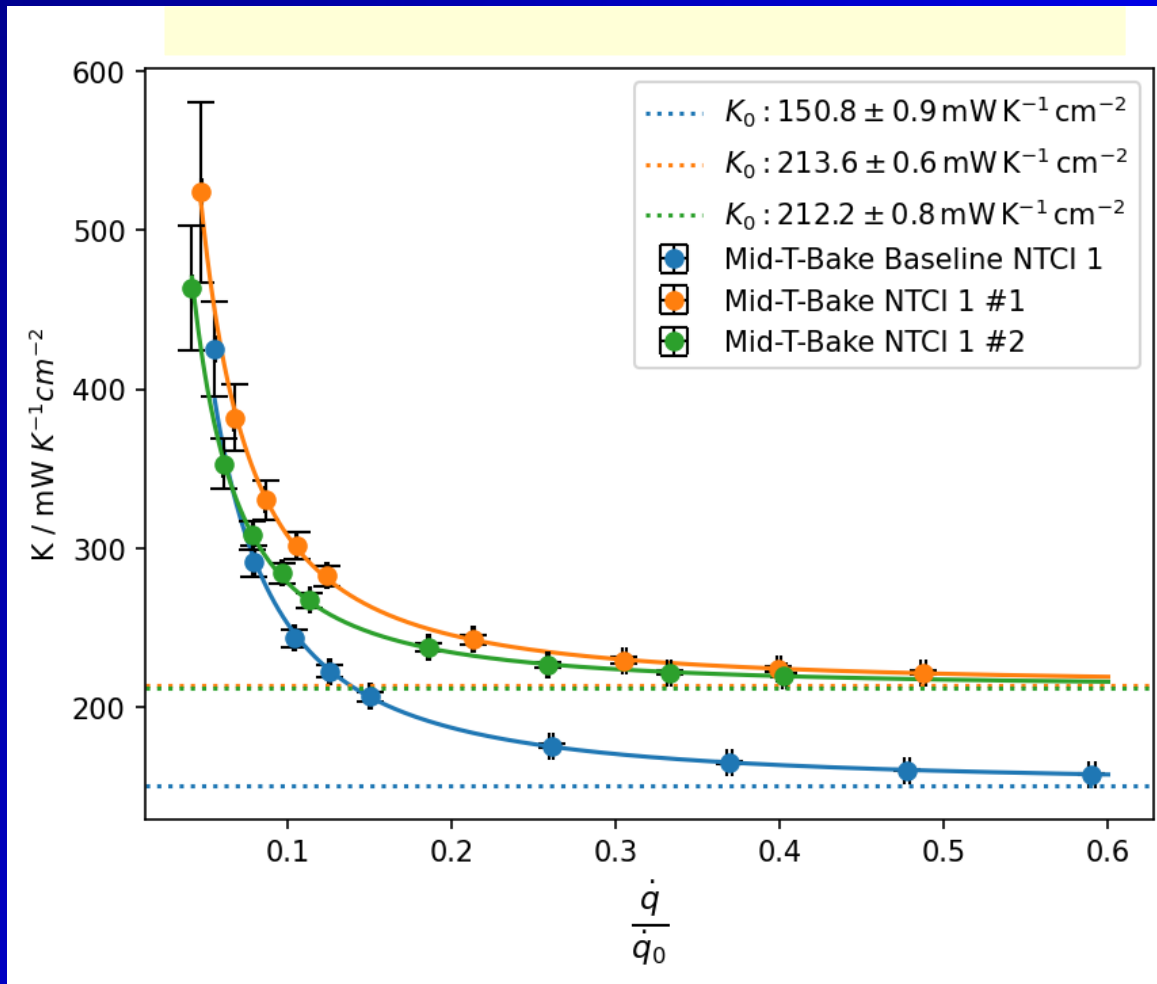
Effects:

- Oxygen diffuses into Nb
- Lower RRR value



<https://www.kitchenaid.com/pinch-of-help/major-appliances/how-to-maximize-oven-space.html>

K_0 for Sample pair 17



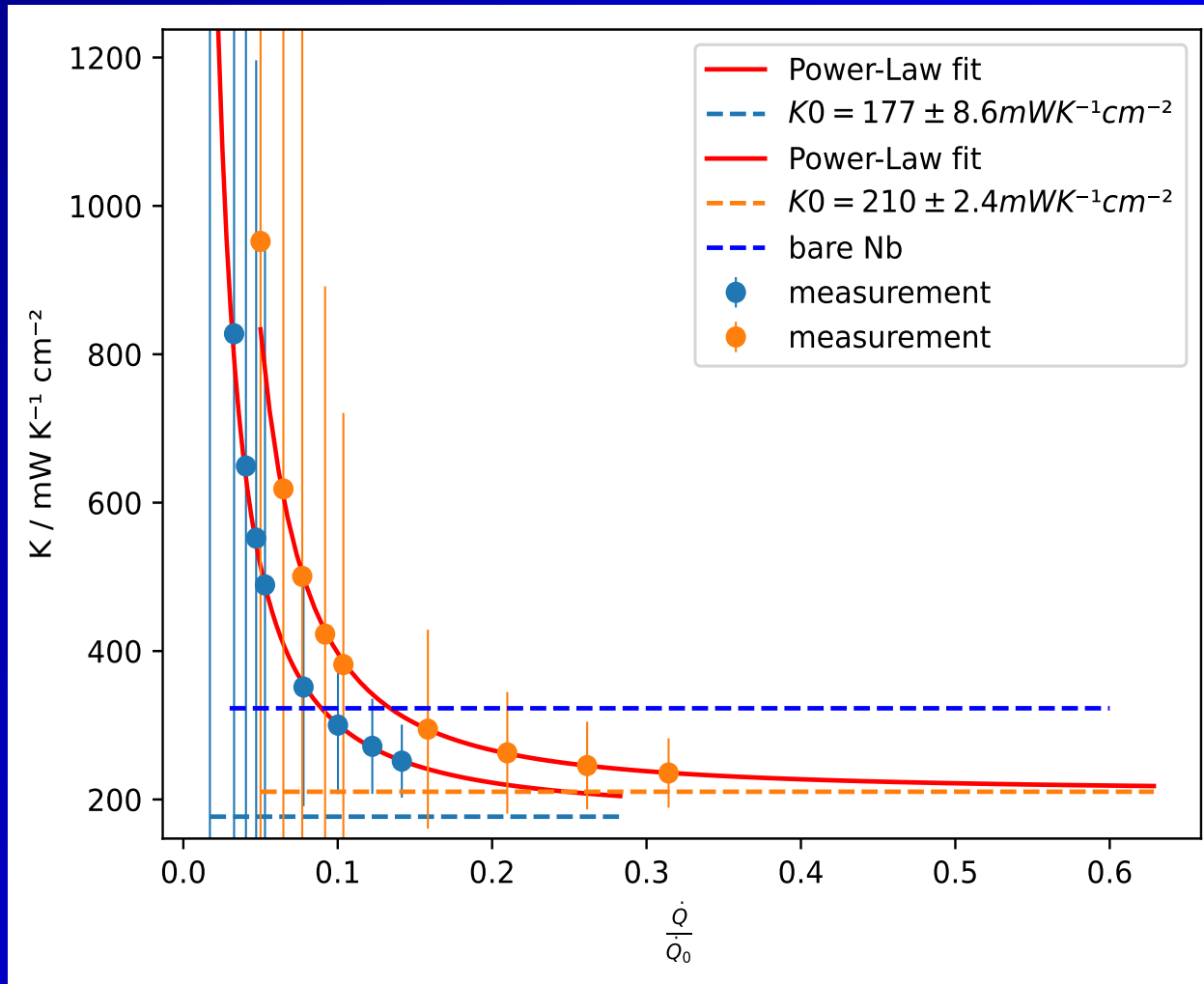
Before Mid-T: (baseline)

- Thermal transmittance:
 $K_0 = 150.8 \pm 0.9 \frac{\text{mW}}{\text{K cm}^2}$
- NTCI 1

After Mid-T:

- Thermal transmittance:
 $K_0 = 213.6 \pm 0.6 \frac{\text{mW}}{\text{K cm}^2}$
- NTCI 1

K_0 for Sample pair 1



Before Mid-T:

- Thermal transmittance:
 $K_0 = 210 \pm 8.6 \frac{\text{mW}}{\text{K cm}^2}$
- NTCI 1

After Mid-T:

- Thermal transmittance:
 $K_0 = 177 \pm 2.4 \frac{\text{mW}}{\text{K cm}^2}$
- NTCI 2

K_0 for Sample pair 1

NTCI's:

- NTCI 2 > NTCI 1
- The difference in K_0 is bigger then it seems

BCP:

- There was a thermal runaway
- Big dents in the Nb
- Not comparable to other samples

After Mid-T:

- Thermal transmittance:
 $K_0 = 177 \pm 8.6 \frac{mW}{Kcm^2}$
- NTCI 2

Before Mid-T:

(baseline)

- Thermal transmittance:
 $K_0 = 210 \pm 2.4 \frac{mW}{Kcm^2}$
- NTCI 1

Comparing data:

Sample pair 1

Before Mid-T:

- Thermal transmittance:
 $K_0 = 210 \pm 2.4 \frac{mW}{Kcm^2}$
- NTCI 1



After Mid-T:

- Thermal transmittance:
 $K_0 = 177 \pm 8.6 \frac{mW}{Kcm^2}$
- **NTCI 2**

Sample pair 17

Before Mid-T:

- Thermal transmittance:
 $K_0 = 150 \pm 0.9 \frac{mW}{Kcm^2}$
- NTCI 1



After Mid-T:

- Thermal transmittance:
 $K_0 = 213 \pm 0.6 \frac{mW}{Kcm^2}$
- NTCI 1

Reason for K_0 changes

Higher roughness:

$$\lambda = \frac{h \cdot c_L(P)}{3.83k_B T}$$

- Lower interface resistance
- ‘trapped’ phonons create new resonance at λ

Heat coefficient: $\lambda = \frac{RRR}{4}$ (rule of thumb)

- Low RRR \rightarrow Low K_0

The rule of thumb might not always work

Future Measurements

NTCI 3 Commissioning

- Sample pair 1 with NTCI 1
- Nb₃Sn (1μm) on Cu w & w/o NbBL (30μm) (w. INFN)
- Nb₃Sn (200nm) on bulk Nb (w. TUDA)
- 2K, 1.8K and 1.5K Measurement for one sample pair



<https://de.dreamstime.com/illustration/checkliste.html>

Helpfull Sources

- L. King Wärmeleitmessungen von beschichtetem und wärmebehandeltem Niob Bachelor Thesis University Hamburg 2024
- Wenskat et al. Thermal transmittance measurements of niobium at cryogenic temperatures, Physica C - submitted
- A. Lorf Einfluss von High- T_c -Beschichtungen auf die Wärmeleitfähigkeit von Niob Bachelor Thesis University Hamburg 2024
- Evidence for thermal boundary resistance effects on superconducting radiofrequency cavity performances

Extra

$$\begin{aligned}
 \lambda(T) &= R(y) \left[\overset{\text{e impuritie scatt.}}{\frac{\rho_{295K}}{L \cdot RRR \cdot T}} + aT^2 \right]^{-1} + \left[\overset{\text{e phonon scatt.}}{\frac{1}{D(y)T^2}} + \overset{\text{lattice phonon scatt.}}{\frac{1}{BI \cdot T^3}} + \overset{\text{lattice grain boundary}}{\frac{1}{BI \cdot T^3}} \right] \\
 R(y) &= \frac{2F_1(-y) + 2y \ln(1 + e^{-y}) + \frac{y^2}{1+e^y}}{2F_1(0)} \\
 \frac{1}{K} &= \left(\frac{d}{\lambda} + R_n \right)
 \end{aligned}$$

Different T measurements to guess the T dependence of $\lambda(T)$

Extra \dot{Q}_0

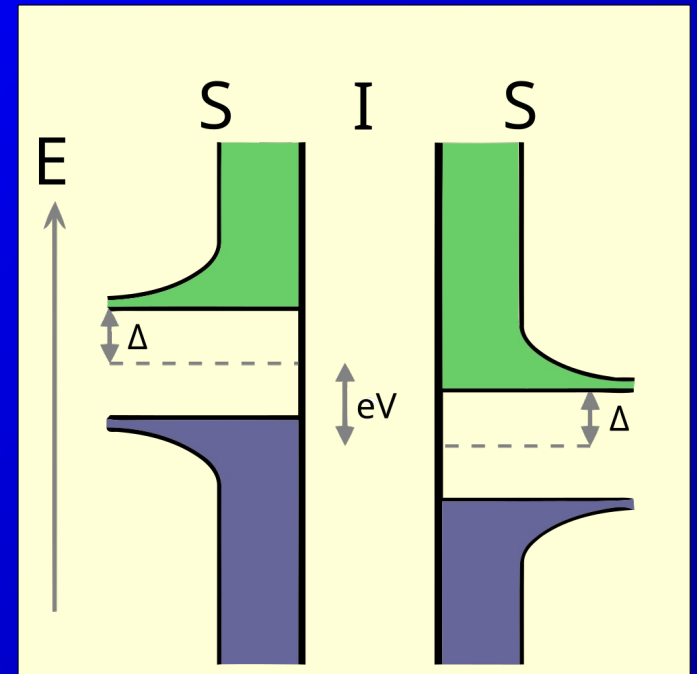
$$K_{old}(\dot{Q}_0) = K_0 + a \left(\dot{Q}_0 \right)^{-n} = 1.01 K_0$$

$$\dot{Q}_0 = \left(\frac{0.01 K_0}{a} \right)^{-\frac{1}{n}}$$

We have to make Q without unit
because of $Q^{-1/n}$

SIS

- Superconductor Insulator Superconductor
- Each film is thinner than λ_L
- T_c is higher than niobium
- PEALD (Plasma Enhanced Atomic Layer Deposition)



https://en.wikipedia.org/wiki/Superconducting_tunnel_junction

Title

- aa